Abstract

A semiconductor device comprising a substrate with a cavity portion for mounting a semiconductor chip is provided to achieve a high reliability and to decrease a size and a fabricating cost. The cavity portion capable of mounting the semiconductor chip (1) at the center portion of the substrate is formed by press forming with a projected portion (13a) of a die (13) while adhering a press shapeable wiring body comprising a copper wiring (12) which becomes wiring material, a barrier layer (11) such as nickel alloy or the like, and a copper foil (10) which is a carrier layer, to a plastic substrate (14,15), so as to have wiring (2) buried into a surface of the substrate and to form a ramp between an inner connection terminal portion connecting to the semiconductor chip (1) and an external connection terminal portion connecting to an external connection terminals (5), the internal and external connection terminal portions being two edge portions of the wiring (2).